

TITLE:
SEMICONDUCTOR STRUCTURE

ABSTRACT

5 Provided is a semiconductor including a substrate, a semiconductor element disposed
on the substrate, an interconnect structure, first and second power deliver lines, and first and
second power deliver network (PDN) structures. The interconnect structure is disposed in
the element region, above the semiconductor element, and electrically connected with the
semiconductor element. The first and the second power deliver lines are disposed above
10 the interconnect structure and electrically connected to the first and the second power
supplies, respectively. The first PDN structure is disposed between the substrate and the
first power deliver line, and connected to the first power deliver line and a lowest circuit
layer of the interconnect structure. The second PDN structure is disposed between the
substrate and the second power deliver line, and connected to the second power deliver line
15 and the lowest circuit layer of the interconnect structure.

FIG. 1A